L Number	Hits	Search Text	DB	Time stamp
1	0	microcircuit and stacked and encapsulant and encasing and removing near insulation	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:16
2	0	microcircuit and stacked and encapsulant and removing near insulation	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:17
3	0	microcircuit and PEM and encapsulant and removing near insulation	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:17
4	0	PEM and encapsulant and removing near insulation	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:17
5	0	PEM and removing near insulation	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:17
6	2601	PEM	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:17
7	80	(PEM) and encapsulation	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:18
8	29	(PEM) and encapsulation and removing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:18
9	394917	(PEM) and removing insulation	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:20
10	0	(PEM) and removing near insulation	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:20

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11	0	(PEM) and removing near encapsulant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:21
12	2	(PEM) and removing same encapsulant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:30
13	0	20020119605.URPN.	USPAT	2003/03/12 12:22
14	21	("4017495" | "4118861" | "4490496" | "4729062" | "4826756" | "4830922" | "4902769" | "4920639" | "4991286" | "5274913" | "5381304" | "5405807" | "5434751" | "5512613" | "5560934" | "5600181" | "5641546" | "5685071" | "5828126" | "5858943" | "6111323").PN.	USPAT	2003/03/12 12:22
15	41	("3801880" | "3864426" | "4012832" | "4370292" | "4529755" | "4604444" | "4626556" | "4632798" | "4663190" | "4729062" | "4738892" | "4983683" | "4985751" | "5037779" | "5043211" | "5061657" | "5064895" | "5072874" | "5120678" | "5128204" | "5140068" | "5160786" | "5199163" | "5250848" | "5264520" | "5274913" | "5286572" | "5298548" | "5300625" | "5313365" | "5326413" | "5371328" | "5381304" | "5434751" | "5457149" | "5460767" | "5471096" | "5474620" | "5498689" | "5821456" | "5863664").PN.	USPAT	2003/03/12 12:24
16	0	(PEM) and removing and grinding near encapsulant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:31
17	0	(PEM) and removing and grinding near (encapsulant or insulation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:32
18	6	removing and grinding near (encapsulant or insulation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:33
19	1	IC and grinding near (encapsulant or insulation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:36

20	0	8153696.URPN.	USPAT	2003/03/12 12:34
21	1	1996-331608.NRAN.	DERWENT	2003/03/12 12:34
22	552166	29/$.ccls. grinding near encapsulant or insulation	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:36
23	166292	29/$.ccls. grinding near (encapsulant or insulation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:37
24	2	29/$.ccls. and grinding near (encapsulant or insulation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:37
25	0	"Albert et al".inv.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:38
26	28	29/840.ccls. and microcircuit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:39
27	3	29/840.ccls. and microcircuit and encapsulant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:42
28	0	20020126459.URPN.	USPAT	2003/03/12 12:42
29	2	"Stackable microcircuit layer "	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:43
30	1	"Stackable microcircuit " and 174/52.2.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:43
31	4077	"Stackable microcircuit layer "and (361/743;29/830 ;29/840 ;29/841 ;361/735 ;361/746).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:44

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32	0	"Stackable microcircuit layer" and (361/743;29/830 ;29/840 ;29/841 ;361/735 ;361/746).ccls. and grinding and removing and encasing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:45
33	1	"Stackable microcircuit layer" and (361/743;29/830 ;29/840 ;29/841 ;361/735 ;361/746).ccls. and grinding and removing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:45
34	1	"Stackable microcircuit layer" and (361/743;29/830 ;29/840 ;29/841 ;361/735 ;361/746).ccls. and removing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:45
35	23	microcircuit and (361/743;29/830 ;29/840 ;29/841 ;361/735 ;361/746).ccls. and removing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:48
36	4	(361/743;29/830 ;29/840 ;29/841 ;361/735 ;361/746).ccls. and encapsulant near removing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 13:07
37	17	("3903590" | "4466181" | "4783695" | "4835704" | "4878991" | "4933042" | "5019946" | "5048179" | "5091769" | "5108825" | "5139969" | "5144747" | "5151776" | "5154793" | "5155068" | "5161093" | "5255431").PN.	USPAT	2003/03/12 12:52
38	8	("3702464" | "4532419" | "4603249" | "4725924" | "4774633" | "4803542" | "4822989" | "4931853").PN.	USPAT	2003/03/12 13:03
39	10	("5207864" | "5386624" | "5406025" | "5483421" | "5638597" | "5739053" | "5785234" | "5813115" | "5816478" | "5873161").PN.	USPAT	2003/03/12 13:05
40	6	("3676745" | "5323295" | "5365403" | "5367439" | "5467251" | "5644103").PN.	USPAT	2003/03/12 13:06
41	60	encapsulant near removal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 13:10
42	0	20010039120.URPN.	USPAT	2003/03/12 13:08
43	14	encapsulant near remove and pad and wire	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 13:13

44	15	("4281031" | "4344809" | "4359360" | "4826556" | "5252179" | "5254237" | "5271798" | "5321222" | "5350737" | "5521360" | "5552112" | "5648038" | "5766496" | "6011249" | "6211499").PN.	USPAT	2003/03/12 13:12
45	4	("3469053" | "5268548" | "5644837" | "5725762").PN.	USPAT	2003/03/12 13:13
46	27	encapsulant and encasing and removing and semiconductor near device	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 13:19
47	19	("4143456" | "4264917" | "4300153" | "4358552" | "4507675" | "4642671" | "4931852" | "4961107" | "5101465" | "5173764" | "5194930" | "5379186" | "5434105" | "5436203" | "5450283" | "5488254" | "5489538" | "5489801" | "5866953").PN.	USPAT	2003/03/12 13:15
48	0	encapsulant and encasing near removing and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 13:19
49	0	encapsulant and encasing near removing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 13:19
50	79	encapsulant near removing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 13:26
51	11	("4460537" | "4615857" | "4910581" | "5417826" | "5434750" | "5542171" | "5557150" | "5635671" | "5656549" | "5780933" | "5963792").PN.	USPAT	2003/03/12 13:24
52	14	("4460537" | "4615857" | "4784974" | "4910581" | "5417826" | "5434750" | "5542171" | "5557150" | "5620928" | "5625235" | "5635671" | "5656549" | "5708567" | "5756380").PN.	USPAT	2003/03/12 13:25
53	0	"removing said encapsulant"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 13:30
54	0	encapsulant near grinding and semiconductor near device	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 13:31

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55	4103	grinding and semiconductor near device	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 13:32
56	10	removing and grinding and encapsulant near material and semiconductor near device	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 13:35
57	0	20030006494.URPN.	USPAT	2003/03/12 13:34
58	15	grinding and encapsulant near material and semiconductor near device	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 13:35
59	33	grinding and encapsulant near material and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 13:36
60	8	("5471087" | "5773323" | "5855727" | "5863810" | "5897338" | "5932061" | "6069392" | "6136212").PN.	USPAT	2003/03/12 13:39
61	23	("H001379" | "3482419" | "3627901" | "3762039" | "3969813" | "4089704" | "4359360" | "4384917" | "4474621" | "4567006" | "4691225" | "4768286" | "4914813" | "4980019" | "5041396" | "5138430" | "5149662" | "5155068" | "5180093" | "5252179" | "5398926" | "5406117" | "5424254").PN.	USPAT	2003/03/12 13:46
62	19	5424254.URPN.	USPAT	2003/03/12 13:49